

4226623/E 06/2025

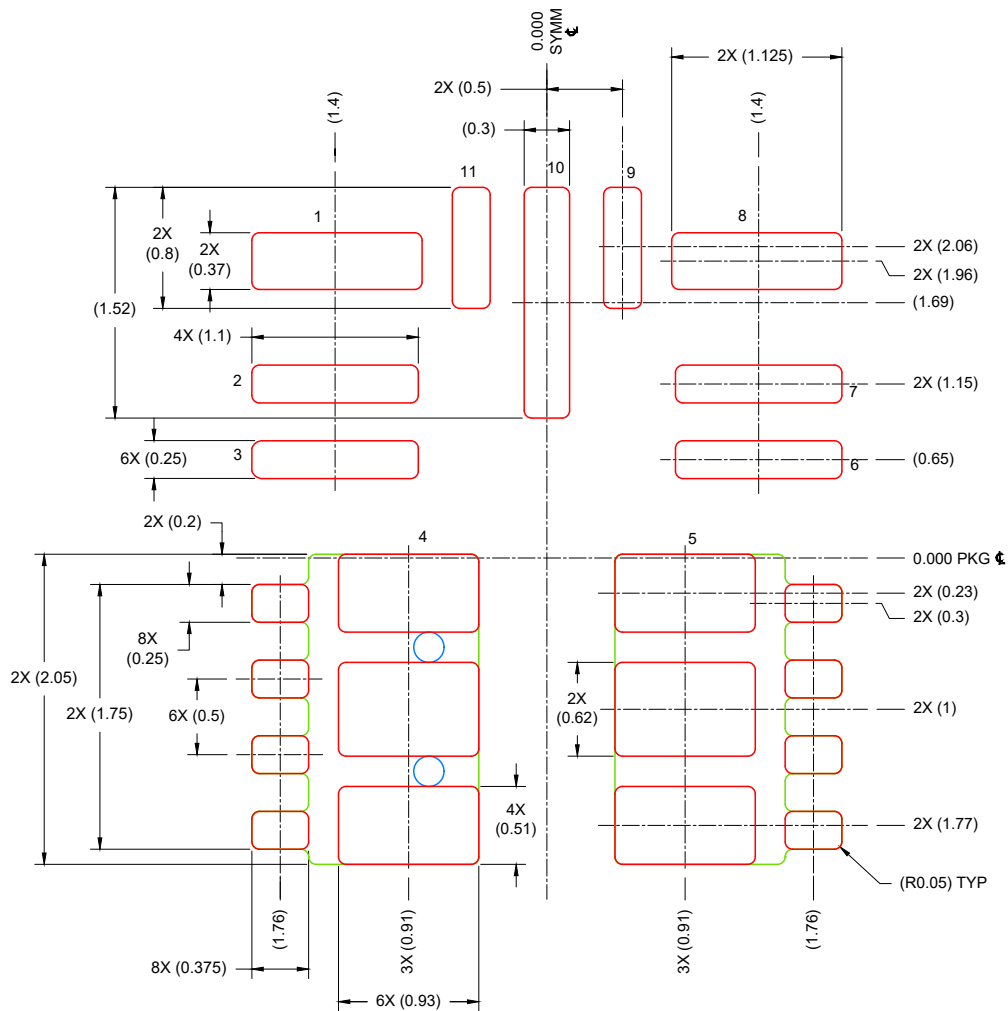
## NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for optimal thermal and mechanical performance.

## PLASTIC QUAD FLAT PACK- NO LEAD



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**SOLDER PASTE EXAMPLE**  
**BASED ON 0.1 mm THICK STENCIL**

PIN 4 & 5:  
 72% SOLDER COVERAGE BY AREA  
 SCALE: 20X

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NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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